



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sehat Sutardja  
Serial No. : 09/966,914  
Filed : September 27, 2001  
Title : IMPROVED INTEGRATED CHIP PACKAGE HAVING INTERMEDIATE  
SUBSTRATE

Art Unit : 2826  
Examiner : Alexander Williams

Commissioner for Patents  
Washington, D.C. 20231

RESPONSE

In response to the action mailed July 31, 2002, please  
amend the application as follows:

In the Claims:

Claims 1, 3, 11-13, 15, 20, 22, 24, and 28 have been  
amended as follows:

1. (Twice Amended) An integrated chip package,  
comprising:

at least one semiconductor chip having a first surface and  
a second surface;

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CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being  
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sufficient postage on the date indicated below and is addressed to the  
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July 7, 2003

Date of Deposit

Signature

Joseph L. Stevenson

Typed or Printed Name of Person Signing Certificate